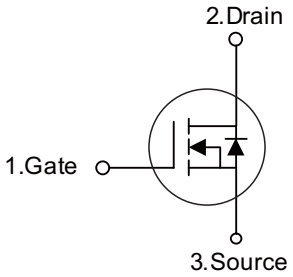
■ PRODUCT CHARACTERISTICS

VDSS	650V
R_{DS}(on)max(@V_{GS} =10 V)	1.1Ω
Qg@type	28nC
ID	8A

Symbol

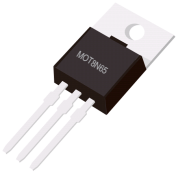


■ APPLICATIONS

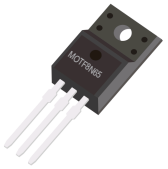
- High efficiency switch mode power supplies
- Electronic lamp ballasts based on half bridge
- LED power supplies

■ FEATURES

* $R_{DS(ON)}$ = 1.1Ω@V_{GS} = 10 V
* Ultra low gate charge
* Low reverse transfer capacitance
* Fast switching capability
* Avalanche energy specified
* Improved dv/dt capability, high ruggedness



TO-220



TO-220F

■ ORDER INFORMATION

Order codes		Package	Packing
Halogen-Free	Halogen		
N/A	MOT8N65F	TO-220F	50 pieces/Tube
N/A	MOT8N65A	TO-220	50 pieces/Tube

■ ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	650	V
Gate-Source Voltage		V_{GSS}	±30	V
Avalanche Current (Note 2)		I_{AR}	8	A
Drain Current	Continuous	I_D	8	A
	Pulsed (Note 2)	I_{DM}	32	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	230	mJ
	Repetitive (Note 2)	E_{AR}	14.7	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.5	V/ns
Power Dissipation	TO-220	P_D	147	W
	TO-220F		48	W
Junction Temperature		T_J	+150	°C
Operating Temperature		T_{OPR}	-55 ~ +150	°C
Storage Temperature		T_{STG}	-55 ~ +150	°C

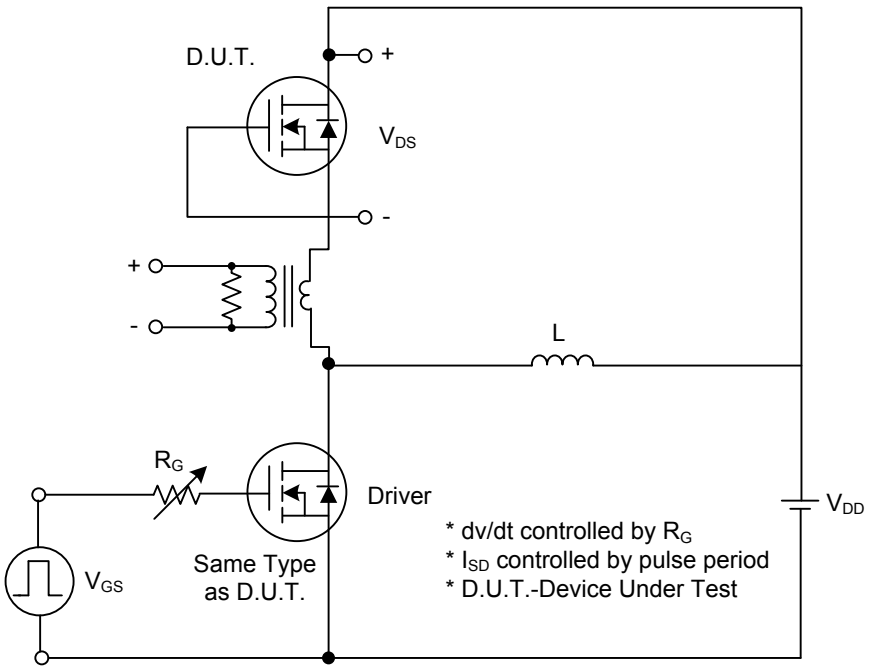
Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating : Pulse width limited by T_J
3. L = 7.1mH, I_{AS} = 8A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C
4. I_{SD} ≤8A, di/dt ≤200A/μs, V_{DD}≤ BV_{DSS}, Starting T_J = 25°C

■ ELECTRICAL CHARACTERISTICS (T_C=25°C, unless otherwise noted)

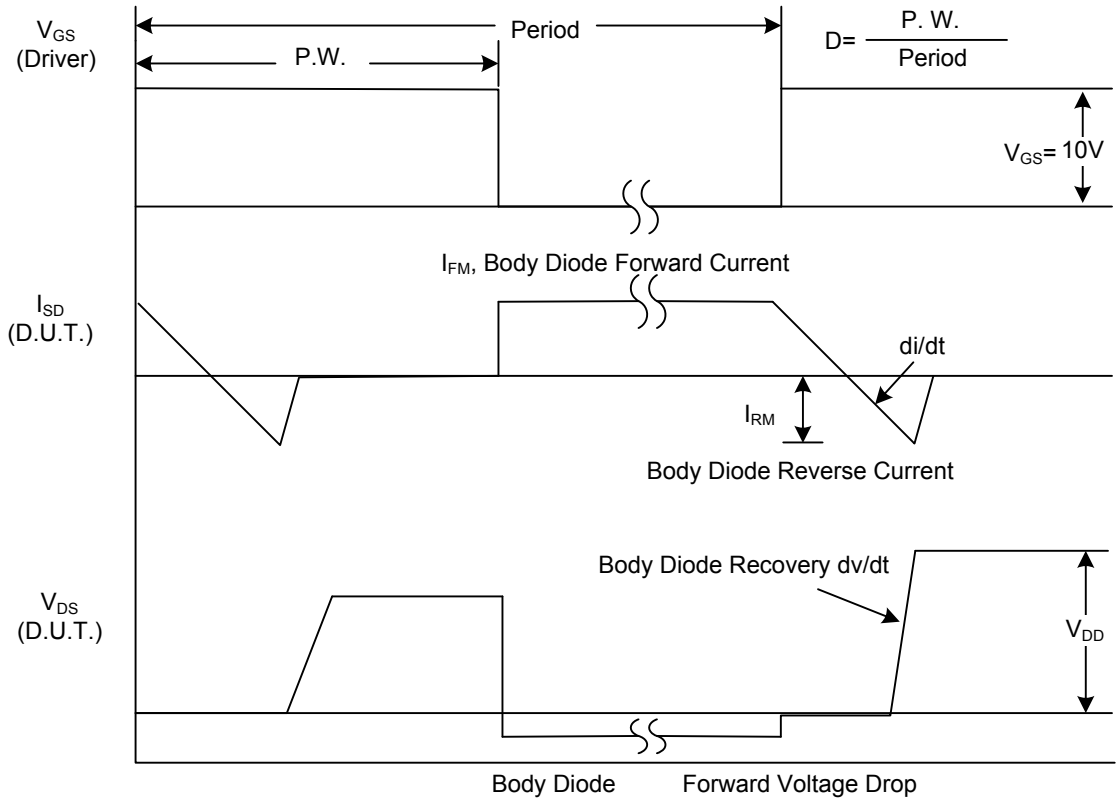
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV_{DSS}	V_{GS} = 0 V, I_D = 250 μA	650			V
Drain-Source Leakage Current		I_{DSS}	V_{DS} = 650 V, V_{GS} = 0 V			10	μA
Gate-Source Leakage Current	Forward	I_{GSS}	V_{GS} = 30 V, V_{DS} = 0 V			100	nA
	Reverse		V_{GS} = -30 V, V_{DS} = 0 V			-100	nA
Breakdown Voltage Temperature Coefficient		$\triangle BV_{DSS}/\triangle T_J$	I_D =250μA,Referenced to 25°C		0.7		V/°C
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	V_{DS} = V_{GS}, I_D = 250 μA	2.0		4.0	V
Static Drain-Source On-State Resistance		$R_{DS(ON)}$	V_{GS} = 10 V, I_D = 4A		0.95	1.1	Ω
DYNAMIC CHARACTERISTICS							
Input Capacitance		C_{ISS}	V_{DS} = 25 V, V_{GS} = 0V, f = 1MHz		965	1255	pF
Output Capacitance		C_{OSS}			105	135	pF
Reverse Transfer Capacitance		C_{RSS}			12	16	pF
SWITCHING CHARACTERISTICS							
Turn-On Delay Time		$t_{D(ON)}$	V_{DD} = 325V, I_D =8A, R_G = 25Ω (Note 1, 2)		16.5	45	ns
Turn-On Rise Time		t_R			60.5	130	ns
Turn-Off Delay Time		$t_{D(OFF)}$			81	170	ns
Turn-Off Fall Time		t_F			64.5	140	ns
Total Gate Charge		Q_G	V_{DS}= 520V,I_D=8A, V_{GS}= 10 V (Note 1, 2)		28	36	nC
Gate-Source Charge		Q_{GS}			4.5		nC
Gate-Drain Charge		Q_{GD}			12		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS							
Drain-Source Diode Forward Voltage		V_{SD}	V_{GS} = 0 V, I_S =8A			1.4	V
Maximum Continuous Drain-Source Diode Forward Current		I_S				8	A
Maximum Pulsed Drain-Source Diode Forward Current		I_{SM}				32	A
Reverse Recovery Time		t_{RR}	V_{GS} = 0 V, I_S =8A, dI_F/dt = 100 A/μs (Note 2)		365		ns
Reverse Recovery Charge		Q_{RR}			3.4		μC

Notes: 1. Pulse Test: Pulse width ≤300μs, Duty cycle≤2%
2. Essentially independent of operating temperature

■ TEST CIRCUITS AND WAVEFORMS

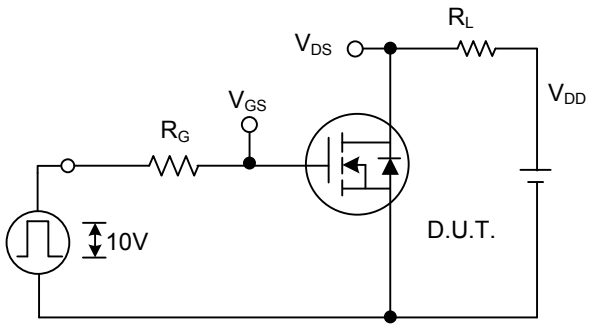


Peak Diode Recovery dv/dt Test Circuit

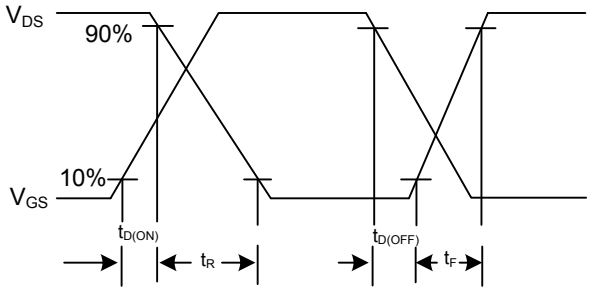


Peak Diode Recovery dv/dt Waveforms

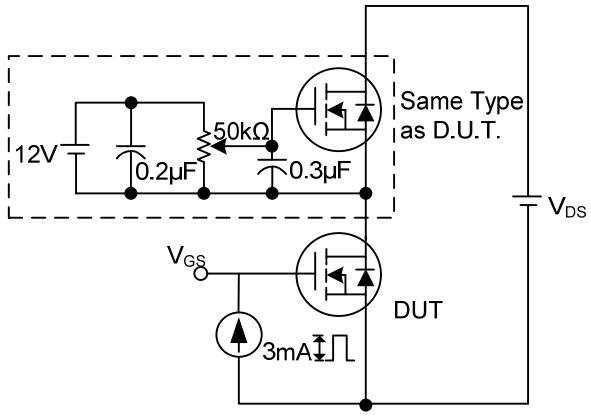
■ TEST CIRCUITS AND WAVEFORMS(Cont.)



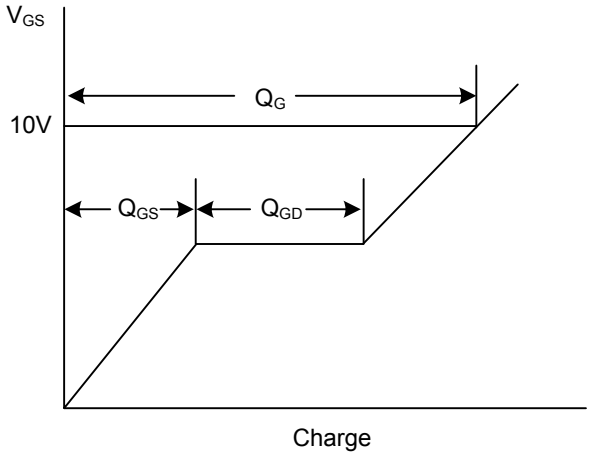
Switching Test Circuit



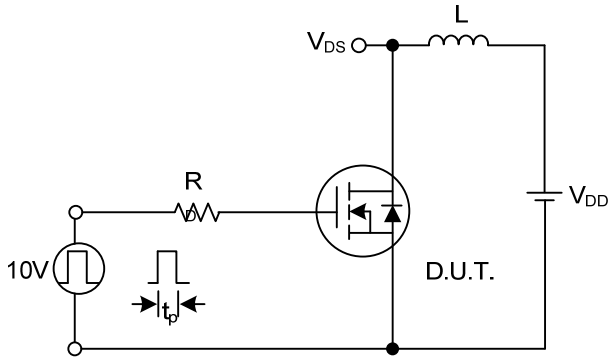
Switching Waveforms



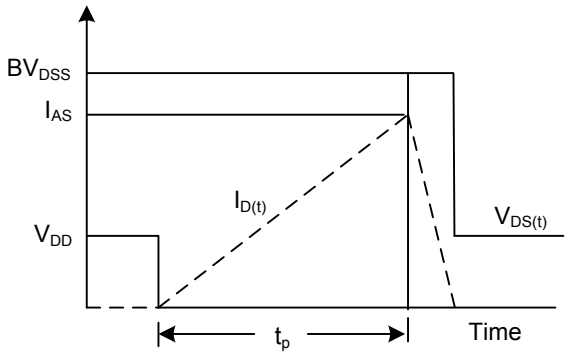
Gate Charge Test Circuit



Gate Charge Waveform



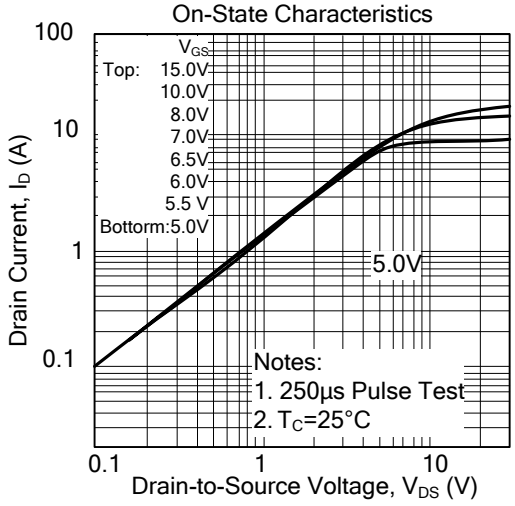
Unclamped Inductive Switching Test Circuit



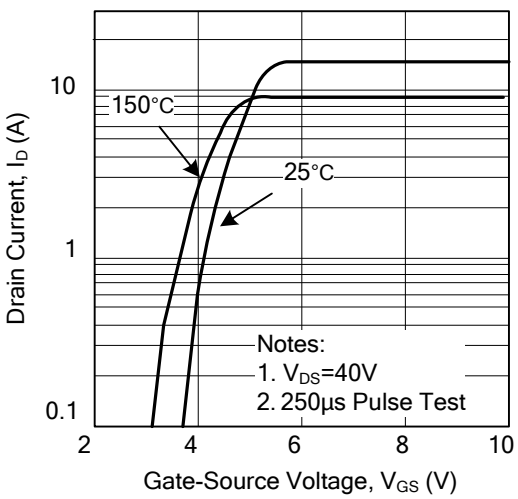
Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS

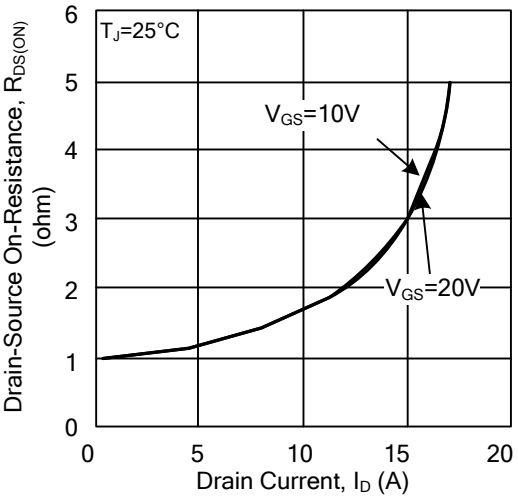
On-State Characteristics



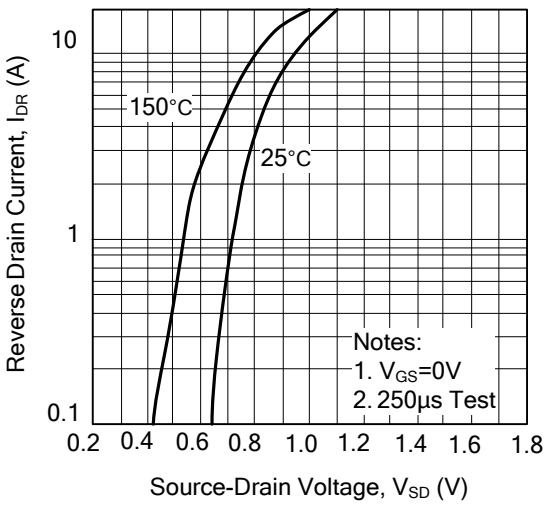
Transfer Characteristics



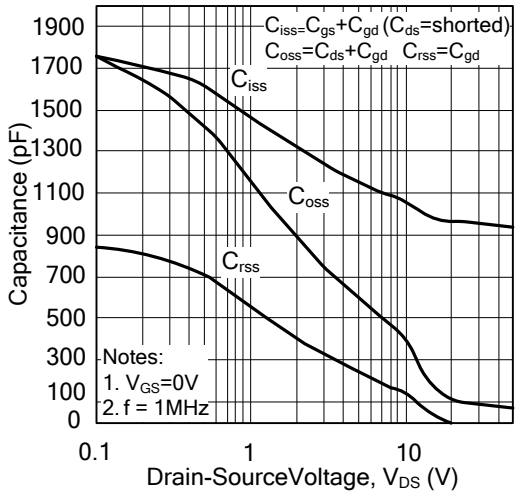
On-Resistance Variation vs. Drain Current and Gate Voltage



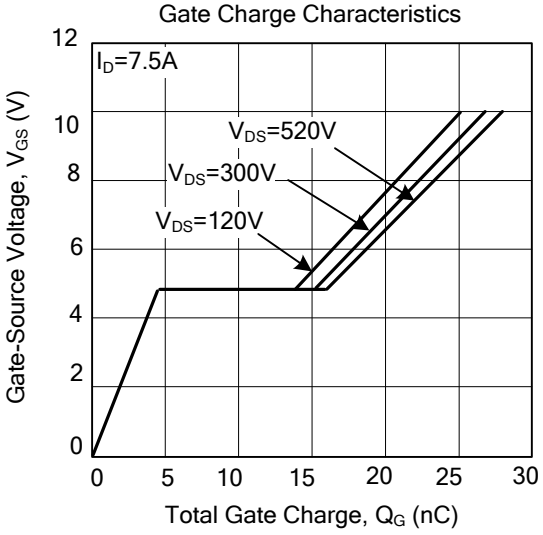
Body Diode Forward Voltage vs. Source Current



Capacitance Characteristics (Non-Repetitive)

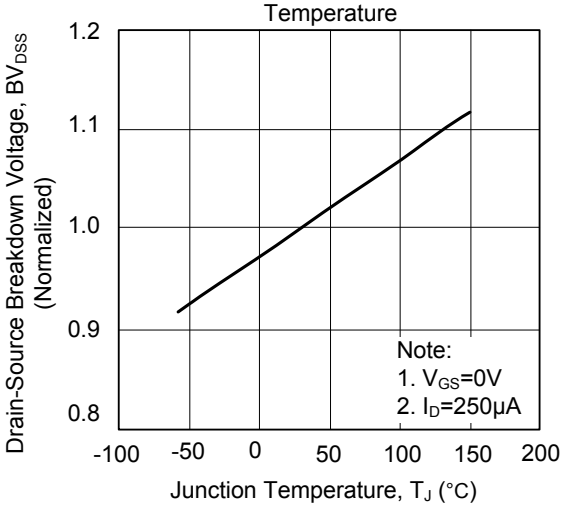


Gate Charge Characteristics

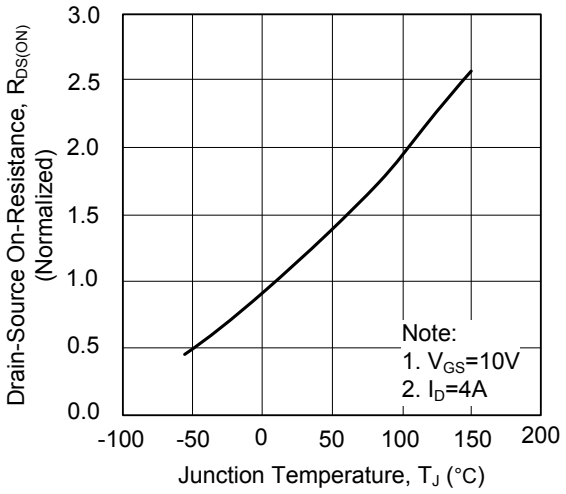


■ TYPICAL CHARACTERISTICS(Cont.)

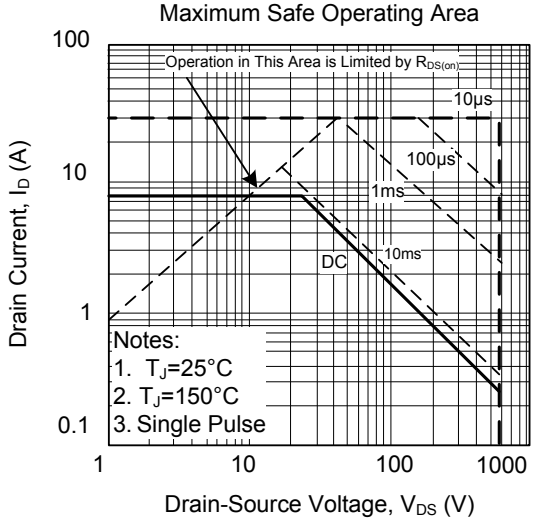
Breakdown Voltage Variation vs. Temperature



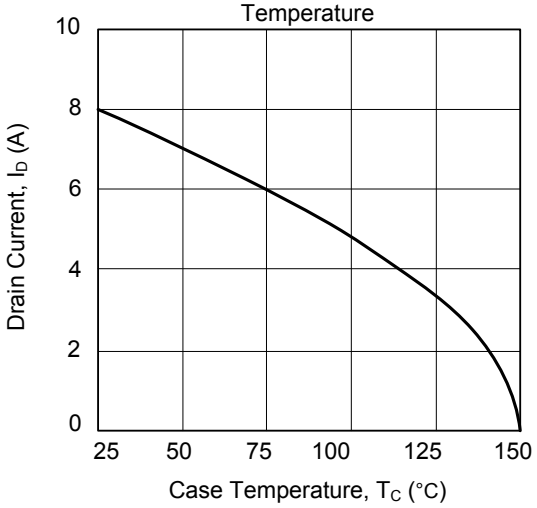
On-Resistance Junction Temperature



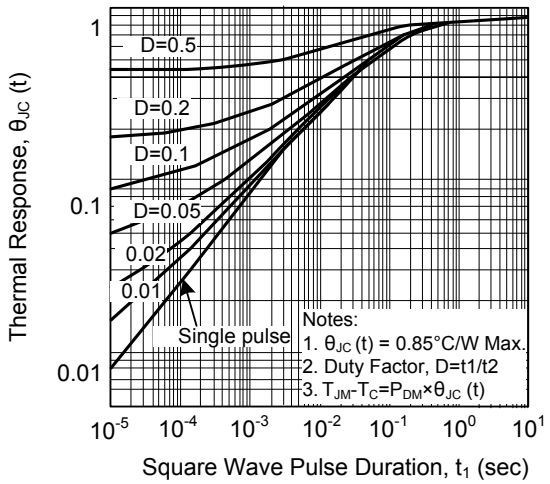
Maximum Safe Operating Area



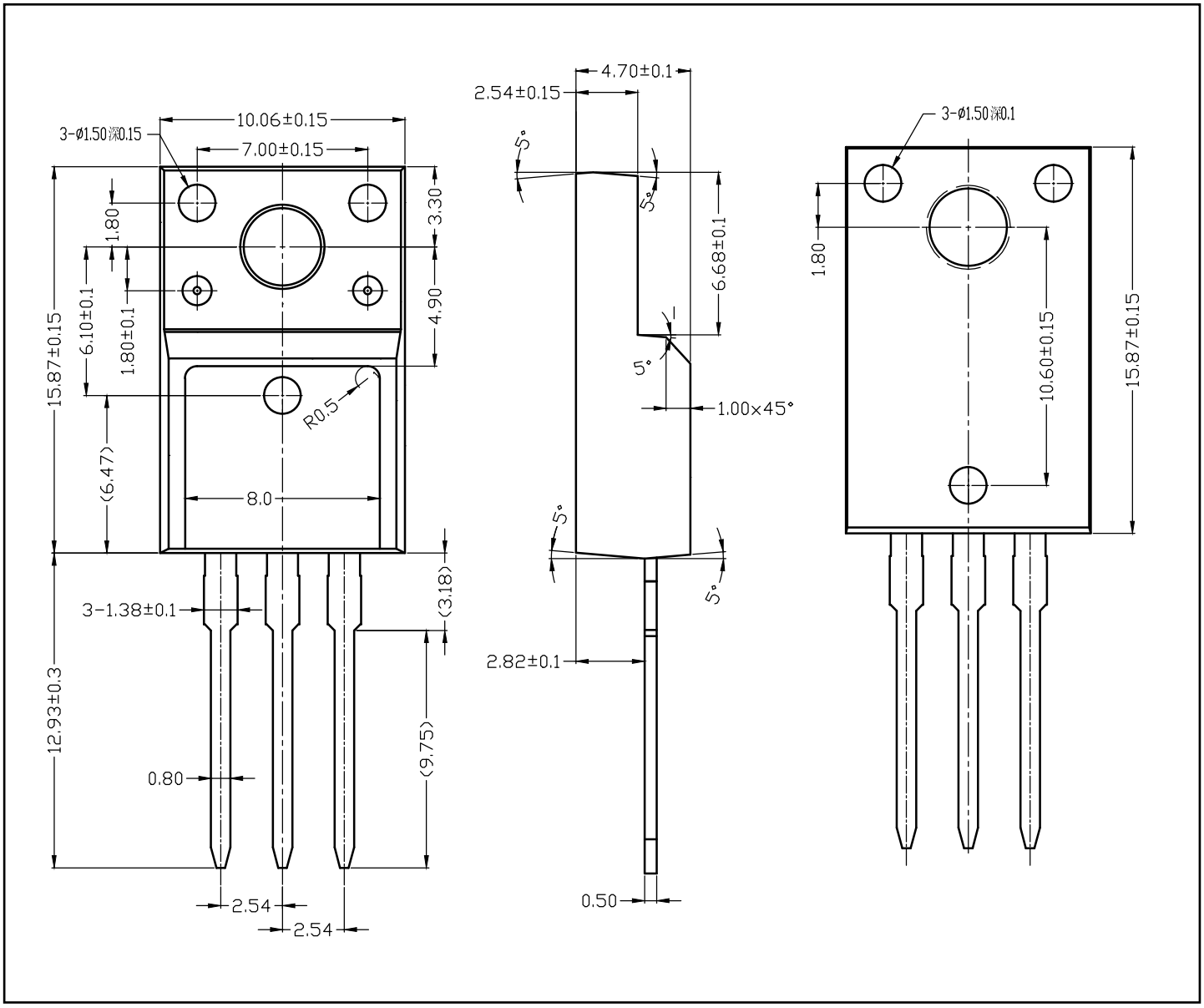
Maximum Drain Current vs. Case Temperature



Transient Thermal Response Curve



■ TO-220F-3L PACKAGE OUTLINE DIMENSIONS



■ TO-220-3L PACKAGE OUTLINE DIMENSIONS